WRITTEN INQUIRIES AND RESPONSES TO THE FOLLOWING DIRECT QUOTE (DQ)

Bid Number: DQ35002 Automatic Fine Wire Bonder

Purchasing Agent: Elevate Quantum
E-Mail: RFQ@ElevateQuantum.org

BID DUE DATE AND TIME: **4, December, 2025, 5:00 PM (Mountain Time)**

SCHEDULE OF ACTIVITIES	DATE	TIME (MT)
DQ Publication	10, November, 2025	
Written Inquiry Deadline	20, November, 2025	3:00 PM
Publication of Responses to Written Inquiries	No later than 25, November, 2025	5:00 PM
DQ Submission Deadline	4, December, 2025	5:00 PM

QUESTIONS:

The following questions have been submitted from vendors related to this DQ and are being provided with responses to all interested parties

1. **The RFQ document mentions both ball and wedge bonding. Are you looking to do primarily wedge bonding with capability for ball bonding? Or primarily ball bonding with capability for wedge bonding?**
    a. We are primarily looking to do wedge bonding at 45 degrees but would be interested in a system that is upgradeable to do some ball bonding in the future, and having upfront knowledge of any necessary optional configurations needed for this.
2. **Is the 31mm Z-stroke cleareance a requirement for a wedge bonding system?**
    a. No, this is a spec for a ball bonding system upgrade. A lower Z-stroke of 19mm will be appropriate for our wedge bonding needs.
3. **Does this process need to have a manual or automatic loading process?**
    a. A manual loading process with the with the option to upgrade to automation in the future would be ideal.
4. **The RFP document specifies closed-loop bond-force control to prevent pad and substrate damage. Would an "open-loop" system be appropiate?**
    a. Yes, a closed-loop system that adjusts parameters during the process is not necessary. An open-loop system that would stop bonding when parameters go beyond process limits is appropriate and sufficient.
5. **For process control monitoring, is process data export acceptable in lieu of statistical process control?**
    a. Yes, process data export is acceptable.